

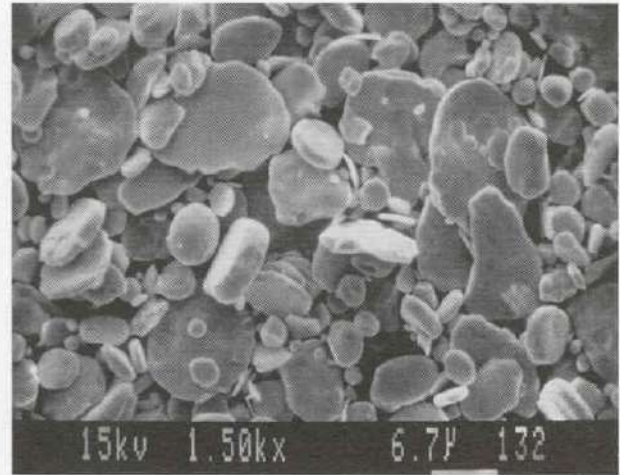
CuLox Flakes—Fines, Intermediates, Coarse

Description

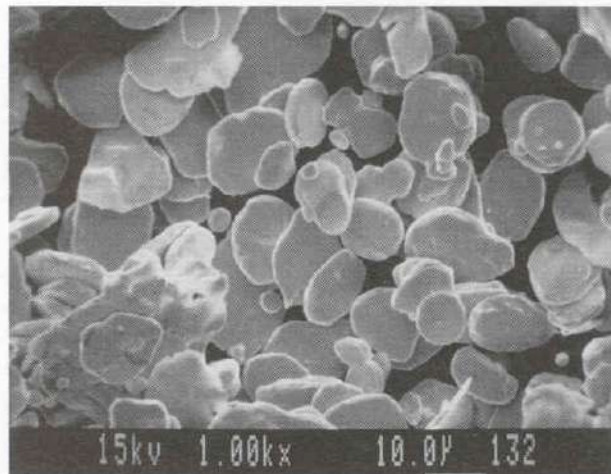
CuLox Flakes are mechanically flattened gas atomized Copper powders. Like our powders, our flake sizes can be customized to suit a wide range of application needs. The flakes are made principally for the electronic industry for a variety of uses.

General Application

CuLox flakes are developed for use in the manufacture of electronic pastes, in conductive inks, and conducting adhesives applications.



Typical SEM Photo of Cu Flake (6030F)
3 Micron Flake



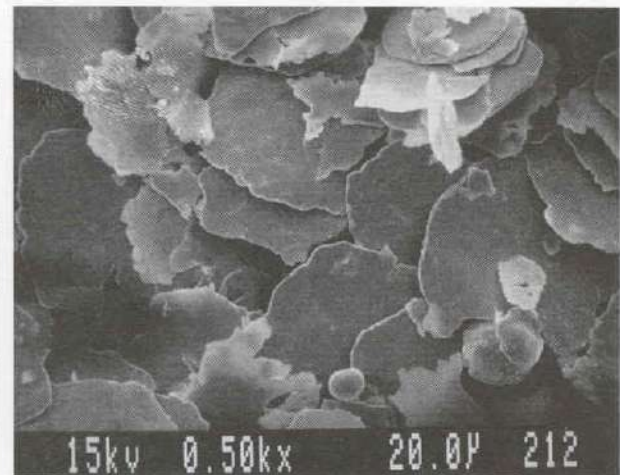
Typical SEM Photo of Cu Flake (6080F)
8 Micron Flake

	Fines		
	6010	6030	6050
Physical Properties	6010	6030	6050
Particle Shape	Flake	Flake	Flake
Med. Size (Microtrac/Horiba)	0.5-1.75	2.5-6.0	4.0-7.5
Surface Area (m ² /g)*	1.0-3.5	0.20-0.65	0.10-0.50
Tap Density (gm/cc)	1.0-2.5	3.0-5.0	3.0-5.0

*Can be customized and controlled

	Intermediates	Coarse
Physical Properties	6080, 6100	6200, 6300
Particle Shape	Flake	Flake
Med. Size (Microtrac/Horiba)	8.0-12.0 Microns	15.0-30.0 Microns
Surface Area (m ² /g)*	0.10-0.50	<0.30
Tap Density(gm/cc)	3.0-5.0	3.5-5.0

*Can be customized and controlled



Typical SEM Photo of Cu Flake (6200F)
20 Micron Flake

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